

# Bill of Materials

TI DESIGNS

TIPD153: Single-Channel Industrial Voltage and Current Output Driver, Isolated, EMC/EMI Tested

Item #	Quantity	Designator	Value	Description	Manufacturer	Part Number
1	11	C1, C5, C9, C10, C12, C15, C16, C17, C18, C19, C21	0.1uF	CAP, CERM, 0.1uF, 50V, +/-10%, X7R, 0603	MuRata	GRM188R71H104KA93D
2	5	C2, C6, C7, C8, C11	100pF	CAP, CERM, 100pF, 50V, +/-5%, C0G/NP0, 0603	AVX	06035A101JAT2A
3	2	C3, C4	10uF	CAP, TANT, 10uF, 50V, +/-10%, 0.8 ohm, 7343-43 SMD	Vishay-Sprague	293D106X9050E2TE3
4	7	C13, C14	1000pF	CAP, CERM, 1000pF, 100V, +/-10%, X7R, 0603	MuRata	GRM188R72A102KA01D
5	1	C20	2200pF	CAP, CERM, 2200pF, 50V, +/-5%, C0G/NP0, 0603	MuRata	GRM1885C1H222JA01D
6	1	C22, C23, C25	0.1uF	CAP, CERM, 0.1uF, 50V, +/-5%, X7R, 0805	AVX	08055C104JAT2A
7	1	C24	0.022uF	CAP, CERM, 0.022uF, 50V, +/-10%, X7R, 0603	TDK	C1608X7R1H223K
8	2	D1, D2		Diode, TVS, Uni, 15V, 600W, SMB	Diodes Inc.	SMBJ15A-13-F
9	1	D3		IC TVS ARRAY 2-LINE 70V SOT-143	Bourns	CD143A-SR70
10	2	D4, D5		DIODE TVS ARRAY 15V SOD323	Bourns	CDSOD323-T15SC
11	1	FB1		FERRITE CHIP 600 OHM 200MA 0603	MuRata	BLM18HG601SN1D
12	1	FB2		BEAD FERRITE 500 OHM 3.0A 3216	Bourns Inc.	MH3261-501Y
13	1	ISO1		ISOLATOR DGTL 25MBPS 4CH 16SOIC	Texas Instruments Inc	ISO7641FCDW
14	1	J2		CONN SOCKET 50PIN .050 R/A SNGL	Mill-Max Manufacturing Corp.	851-43-050-20-001000
15	2	J3, J4		TERMINAL BLOCK 3.5MM 2POS PCB	On Shore Technology Inc	ED555/2DS
16	1	J1		TERMINAL BLOCK 3.5MM 3POS PCB	On Shore Technology Inc	ED555/3DS
17	2	R1, R2	15	RES, 15 ohm, 5%, 0.1W, 0603	Vishay-Dale	CRCW060315R0JNEA
18	1	R3	15	RES 15 OHM 1/2W 1% 1210 SMD	Panasonic Electronic Components	ERJ-14NF15R0J
19	1	Rset	DNI	RES, 15.0k ohm, 0.1%, 0.1W, 0603	Yageo America	RT0603BRD0715KL
20	1	U1		DAC8760 DAC-XTR RTA QFN-40	Texas Instruments	DAC8760

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